

WHAT IS CLAIMED IS:

1. An image capture device, comprising:

5 a substrate having a first side, a second side and a conductor pattern;

 an image sensor provided on the first side of the substrate and electrically
connected to the conductor pattern;

10 a first die provided on the second side of the substrate and electrically
connected to the conductor pattern;

 a second die stacked on the first die and electrically connected to the
conductor pattern, and

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 a frame provided on the first side of the substrate to receive the image sensor
therein, wherein the frame has a window aligned with the image sensor.

2. The image capture device as defined in claim 1, further comprising an
20 insulating layer provided on the second side of the substrate to cover the first die and
the second die.

3. The image capture device as defined in claim 2, further comprising a heat
sink provided to the insulating layer.

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4. The image capture device as defined in claim 3, wherein the insulating layer is a metal plate.

5. The image capture device as defined in claim 1, further comprising a glass
5 provided to the frame to seal the window.

6. The image capture device as defined in claim 1, further comprising at least a lens provided in the window of the frame.

10 7. The image capture device as defined in claim 5, further comprising at least a lens provided in the window of the frame.

8. The image capture device as defined in claim 1, wherein the first die is a memory chip and the second die is a digital signal processor.
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9. The image capture device as defined in claim 1, wherein the first die is a digital signal processor and the second die is a memory chip.

10. The image capture device as defined in claim 1, wherein the substrate is
20 provided with a cavity and the first die has at least a portion thereof received in the cavity.

11. The image capture device as defined in claim 10, wherein the cavity runs through the substrate from the first side to the second side and the image sensor has a
25 portion aligned with the cavity and the first die is bonded on a bottom of the image

sensor.

12. The image capture device as defined in claim 10, wherein the cavity is close at the first side of the substrate and is open at the second side of the substrate and
5 the first die is bonded on a bottom of the cavity.